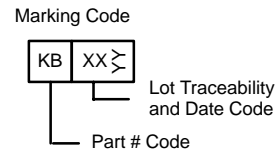
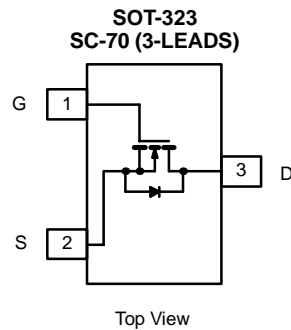




N-Channel 25-V (D-S) MOSFET

TrenchFET[®]
Power MOSFETs

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
25	0.350 @ $V_{GS} = 4.5$ V	0.75
	0.450 @ $V_{GS} = 2.5$ V	0.66



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)					
Parameter	Symbol	5 secs	Steady State	Unit	
Drain-Source Voltage	V_{DS}	25		V	
Gate-Source Voltage	V_{GS}	± 8			
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	$T_A = 25^\circ\text{C}$	0.75	0.70	A
		$T_A = 70^\circ\text{C}$	0.60	0.56	
Pulsed Drain Current	I_{DM}	3.0			
Continuous Diode Current (Diode Conduction) ^a	I_S	0.28	0.24		
Maximum Power Dissipation ^a	P_D	$T_A = 25^\circ\text{C}$	0.33	0.29	W
		$T_A = 70^\circ\text{C}$	0.21	0.19	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150		$^\circ\text{C}$	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	$t \leq 5$ sec	R_{thJA}	315	375	$^\circ\text{C/W}$
	Steady State		380	450	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	285	340	

Notes

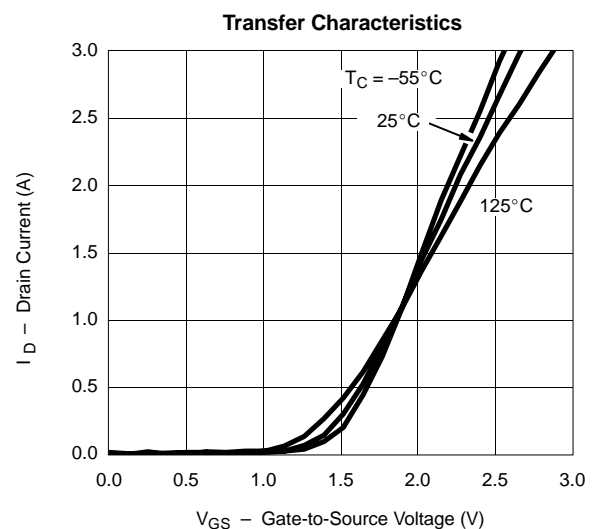
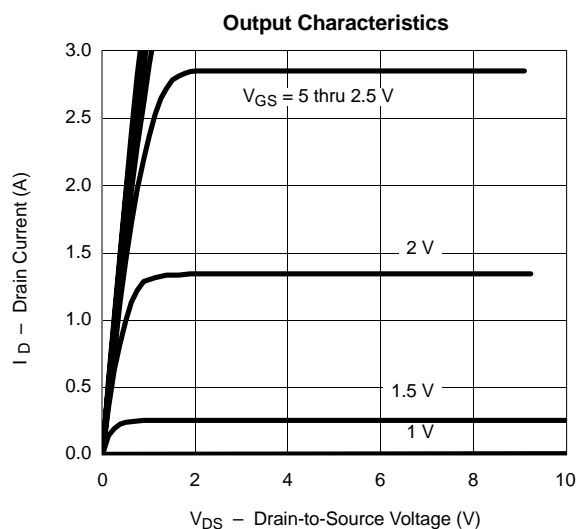
a. Surface Mounted on 1" x 1" FR4 Board.

SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.6			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 70^\circ\text{C}$			5	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	3.0			A
Drain-Source On-State Resistance ^a	$r_{DS(on)}$	$V_{GS} = 4.5 \text{ V}, I_D = 0.75 \text{ A}$		0.280	0.350	Ω
		$V_{GS} = 2.5 \text{ V}, I_D = 0.50 \text{ A}$		0.355	0.450	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 0.75 \text{ A}$		1.5		S
Diode Forward Voltage ^a	V_{SD}	$I_S = 0.24 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.75 \text{ A}$		1.85	2.8	nC
Gate-Source Charge	Q_{gs}			0.15		
Gate-Drain Charge	Q_{gd}			0.82		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15 \text{ V}, R_L = 20 \Omega$ $I_D \cong 0.75 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_G = 6 \Omega$		11	20	ns
Rise Time	t_r			18	30	
Turn-Off Delay Time	$t_{d(off)}$			17	30	
Fall Time	t_f			11	20	
Source-Drain Reverse Recovery Time	t_{rr}		$I_F = 0.24 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		30	

Notes

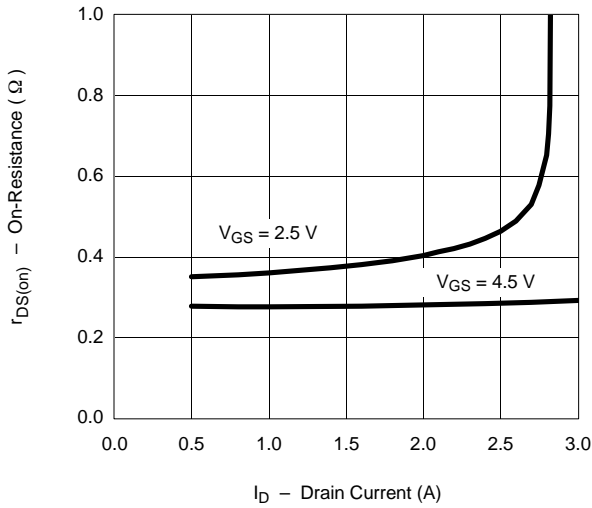
- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

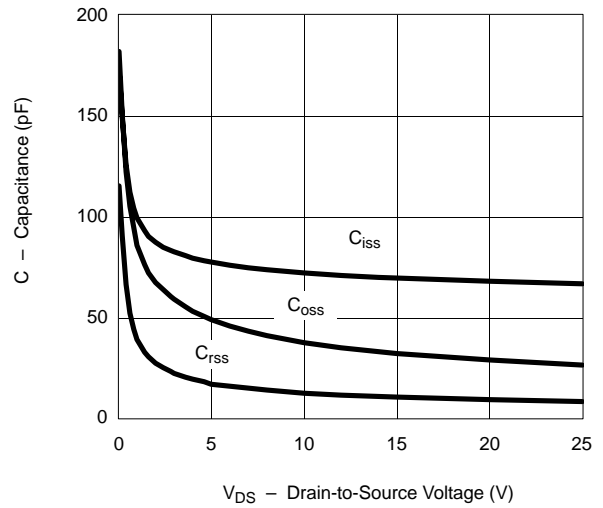


TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)

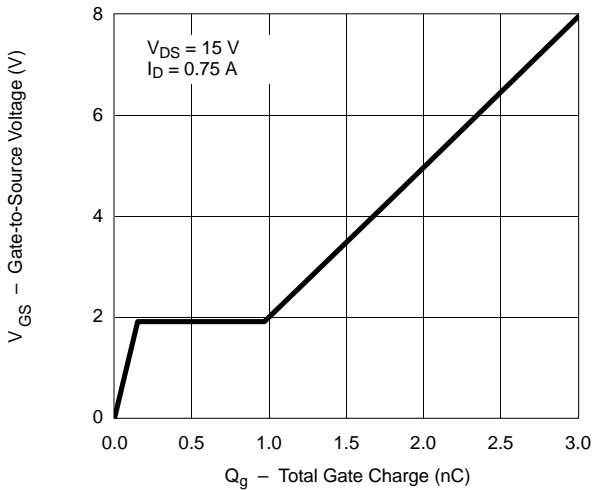
On-Resistance vs. Drain Current



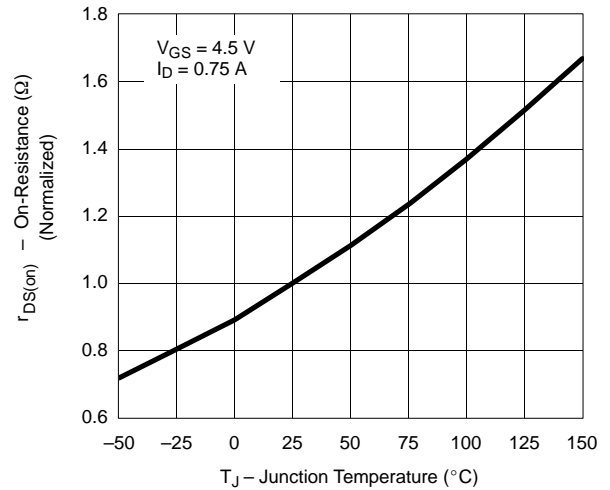
Capacitance



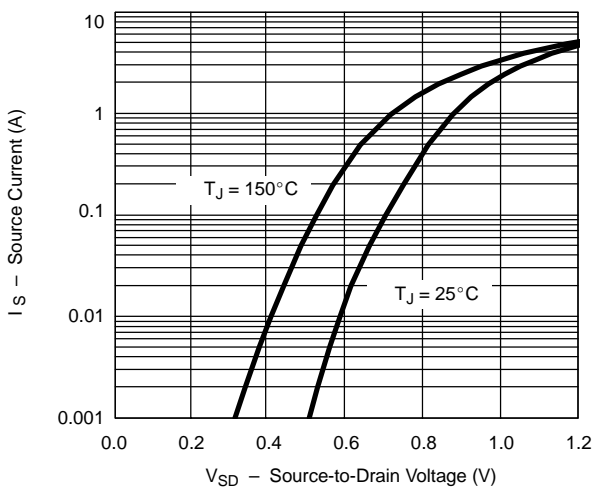
Gate Charge



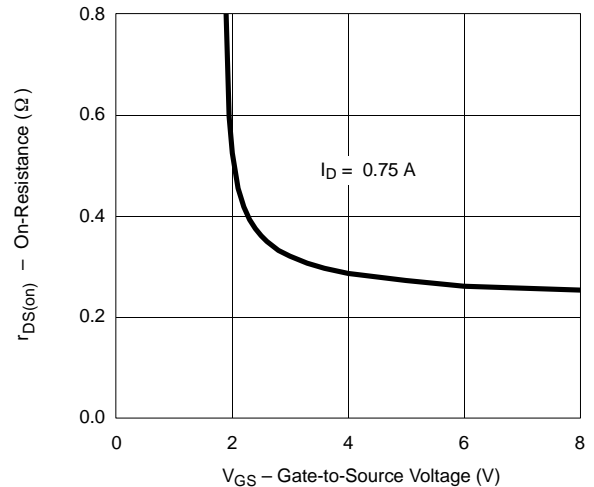
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)

